

QUALCOMM

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13 November 2017

Mr. Mirko Cano Soveri Mr. John Meredith ETSI, MCC 650, route des Lucioles 06921 Sophia-Antipolis France

Subject: Nomination of candidate for the 3GPP TSG SA WG3 Vice-Chairman

Dear Mr. Soveri and Mr. Meredith:

I am pleased to inform you that Qualcomm, through its ATIS 3GPP affiliation, is nominating Adrian Escott as a candidate for the position of 3GPP TSG SA WG3 Vice-Chairman at the upcoming election in SA#89.

In proposing Adrian for the position of 3GPP TSG SA WG3 Vice-Chairman, Qualcomm will fully support Adrian in the vice-chairmanship role. Qualcomm remains fully committed to the success of 3GPP and its diverse ecosystem.

Adrian Escott is informed about and aware of the antitrust/competition laws and regulations of relevant jurisdictions. He will comply with such laws while acting in his capacity as TSG SA WG3 Vice-Chairman.

Adrian is currently a TSG SA WG3 Vice-Chairman; he was first appointed in November 2015. A brief curriculum vitae of Adrian is attached.

Best Regards,

Edward G. Tiedemann, Jr.

Senior Vice-President, Engineering

QUALCOMM Technologies, Inc.

Adrian Escott

Adrian graduated in 1990 with a BA in Mathematic from the University of Oxford and also obtained a PhD from Royal Holloway, University on London in 1994.

Adrian has been working at Qualcomm since 2005. He initially worked in the 3GPP2 standards team and was chair of 3GPP2 security group for some time. Since early 2007, he has been Qualcomm lead representative in SA WG3. During this time, he has been heavily involved in the work of SA WG3 and has been rapporteur for several work items in SA WG3, e.g. Relay Nodes and the ProSe security work. He has been SA3 Vice-chair since November 2015.